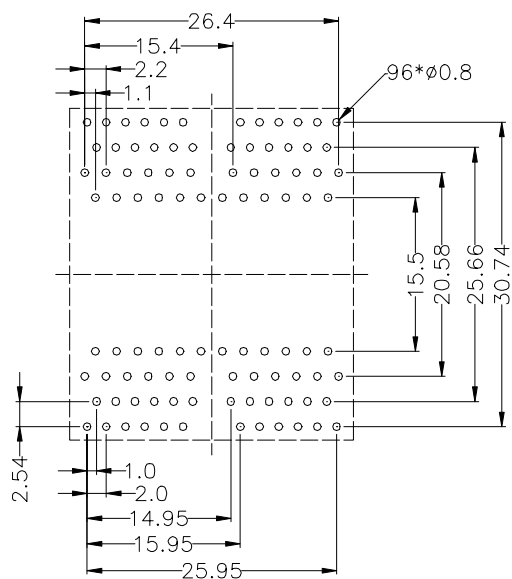
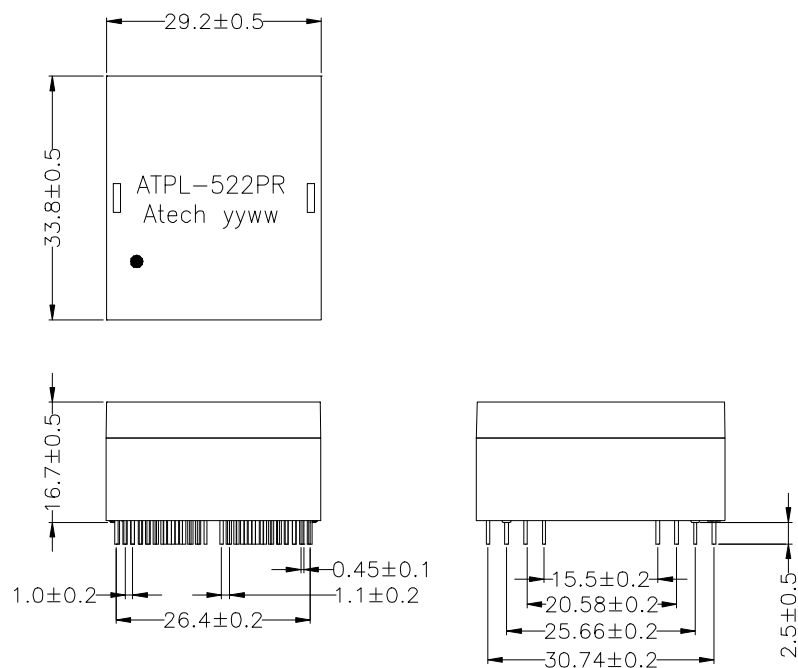
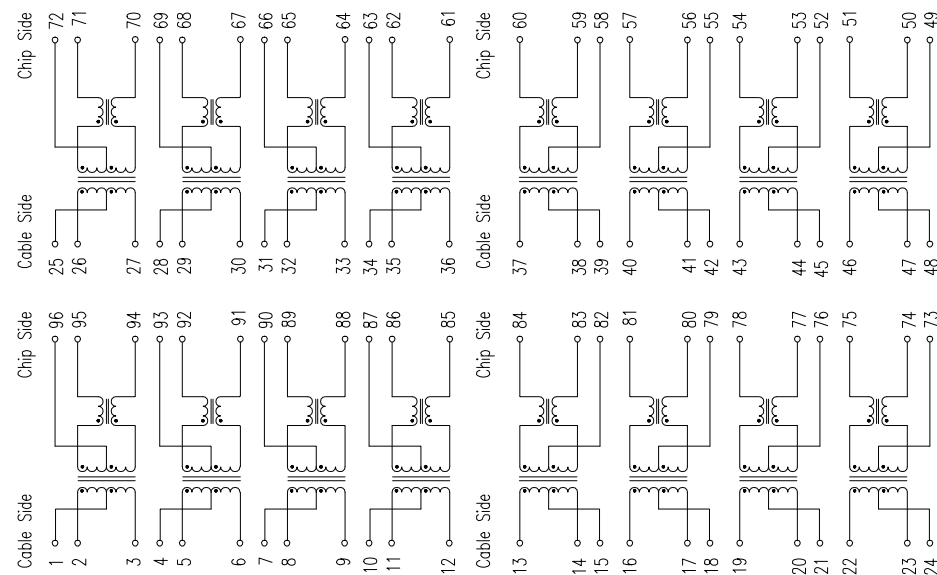




PCB Layout mounting Hole(Top View)



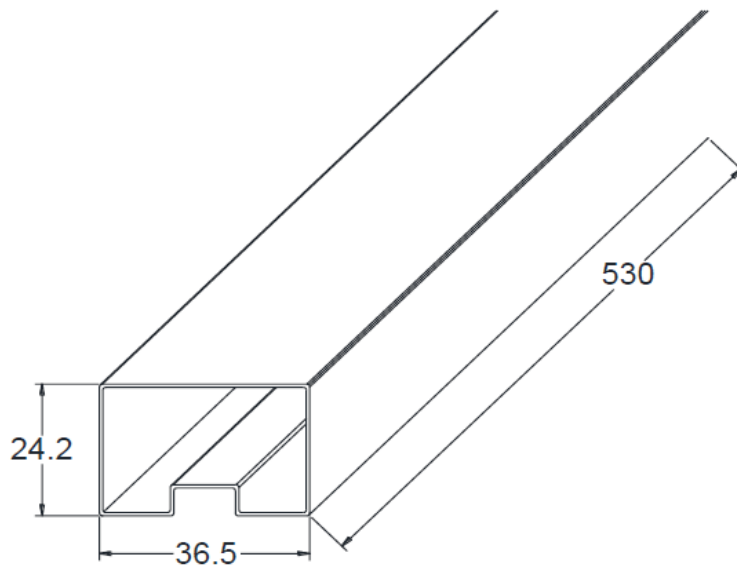
* RoHS COMPLIANT

ELECTRICAL CHARACTERISTICS@25°C

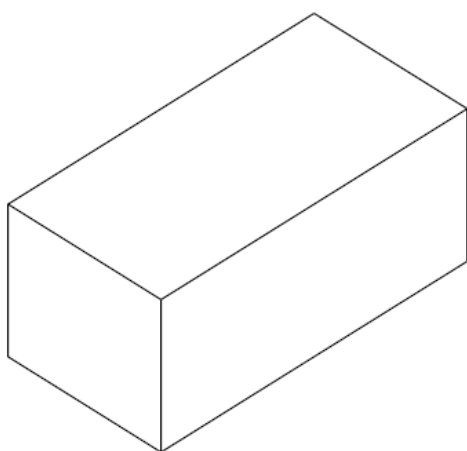
1. OCL : (@100kHz, 0.1V With 8mA DC Bias) : 200uH MIN.
2. LEAKAGE INDUCTANCE : (@100kHz, 0.1V) : 0.5uH MAX.
3. DCR : 1.0Ω MAX.
4. TURNS RATIO : 1CT : 1CT ±5%
5. INSERTION LOSS : (@1-100MHz) : -1.0dB MAX.
(@100-200MHz) : -2.0dB MAX.
6. RETURN LOSS : (@1≤f≤40MHz) : -16dB MIN.
(@40≤f≤250MHz) : -16 + 10Log(f/40)dB MIN,
where f is in MHz
7. CROSS TALK : (@1-250MHz) : -30dB MIN.
8. COMMON MODE REJECTION : (@1-250MHz) : -30dB MIN.
9. ISOLATION HIPOT : (@1500VAC, 1mA, 60S)
10. PoE Support 15W : Each channel support 350mA DC balance current
11. OPERATING TEMPERATURE : 0°C TO +70°C
12. STORAGE TEMPERATURE : -40°C TO +85°C

								TITLE	2.5G/5G BASE-T TRANSFORMER
								DWG. NO.	ATPL-522PR
RELEASE		03/22/2021	SHIRLEY	BETTY	BETTY	UNITS:	SAFETY		SHEET 1 of 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	M/M			
						DATE	P/N:		DRAW
REVISIONS						03/22/21		SHIRLEY	

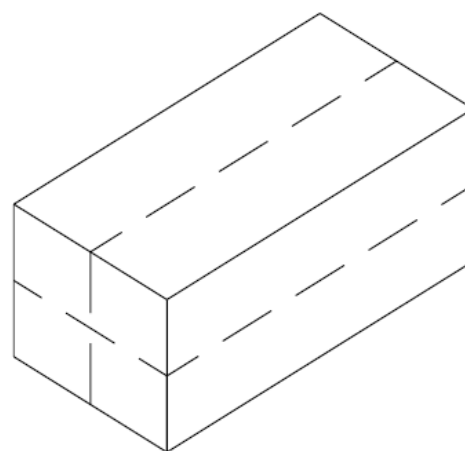
Package :



Tube: 530*24.2*36.5mm



Inner Carton: L575*W170*H87mm



Export Carton: L583*W380*H210mm

Package Quantity:

One Tube=17Pcs

One Inner Carton=17*16=272Pcs

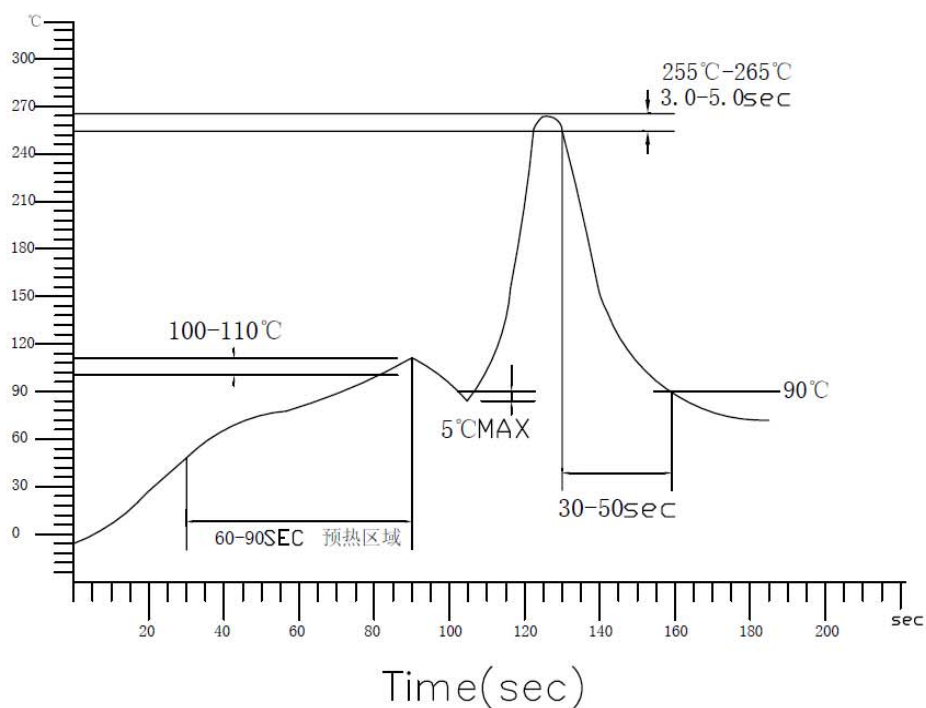
One Export Carton=272*4=1088Pcs

6. Soldering Heat Withstanding Survey (DIP)

Pb-free Soldering Heat Withstanding Survey(DIP)

Reflow conditions	Preheat area	Time at 220℃ or higher	Peak Temp	Holding time at 260℃ temp
Recommended conditions	Max 120s	Max 30s	260℃	Max 6S

Soldering Temp.profile



Soldering conditions	Soldering Temp.	Heating Time
Recommended conditions	260℃±5℃	Max 6 sec

Soldering Iron Conditions	Soldering Iron Temp	Heating Time
Recommended conditions	350±10℃	Max 5 sec

Part Electrode Plating Constitution	Sn.CU
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Any other series applicable same conditions	NO
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Packing Configuration	TRAY
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